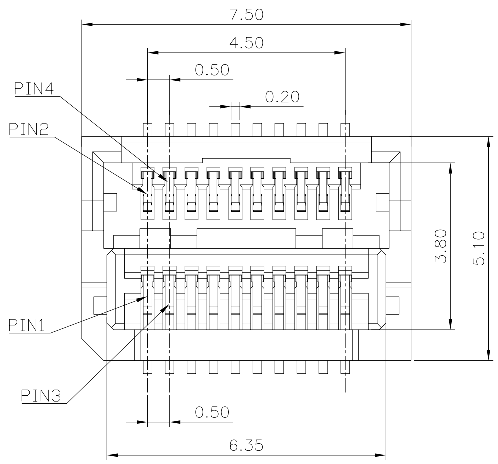
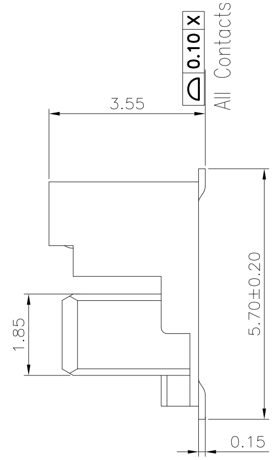
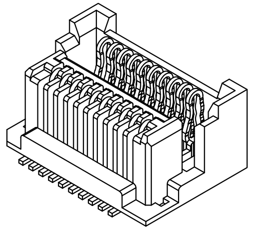
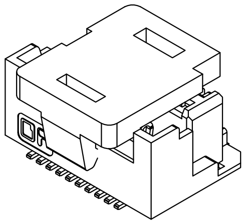
REV.	SPECIFICATION	ECN NO.	APPD.
R2		ECN220358	









Materials and Plating:

Housing: LCP, UL94V-0, Black.

Contact: Copper Alloy.

15u" Gold Plated on Contact Area and Gold Flash on Solder Tail over 50u" Nickel.

Electrical Characteristics:

Current Rating: 0.5 AMP.

Dielectric Withstanding: AC 500V for 1 Minute.

Insulation Resistance: 500MΩ min. at DC 150V.

Contact Resistance: 30mΩ max.at DC 100mA.

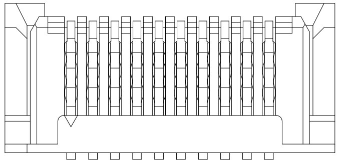
Operating Temperature: -40°C ~ +125°C

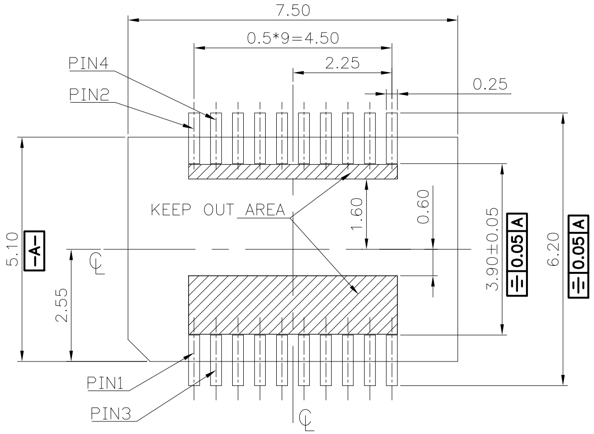
***RoHS Compliant**

Support Speed Rates to 20Gbps @-3dB.

Note 1:

Comply with IPC 7525-A





P.C.Board Layout

(Tolerance:±0.05)

2330- 20 G 15 D N 1 T -P

Series
No. of Position
G: Gold Plated
15: 15u"
D: SMD Type
N: Without Post
1: Stack Height 4mm
T: Tape & Reel Package
P: With Plastic Cap

HERMAPHRODITIC CONNECTOR MATING	
CONNECTOR POSITION	MATES WITH CONNECTOR POSITION
1	2
3	4
5	6
7	8
9	10
ETC.	

Tolerances	Dwg. No.	2330–DS20–001		
x = ±0.5	Projection			
.x = ±0.25	Unit	mm	Scale	1:1
.xx = ±0.15	Drawn By	ZY 3/24'22		

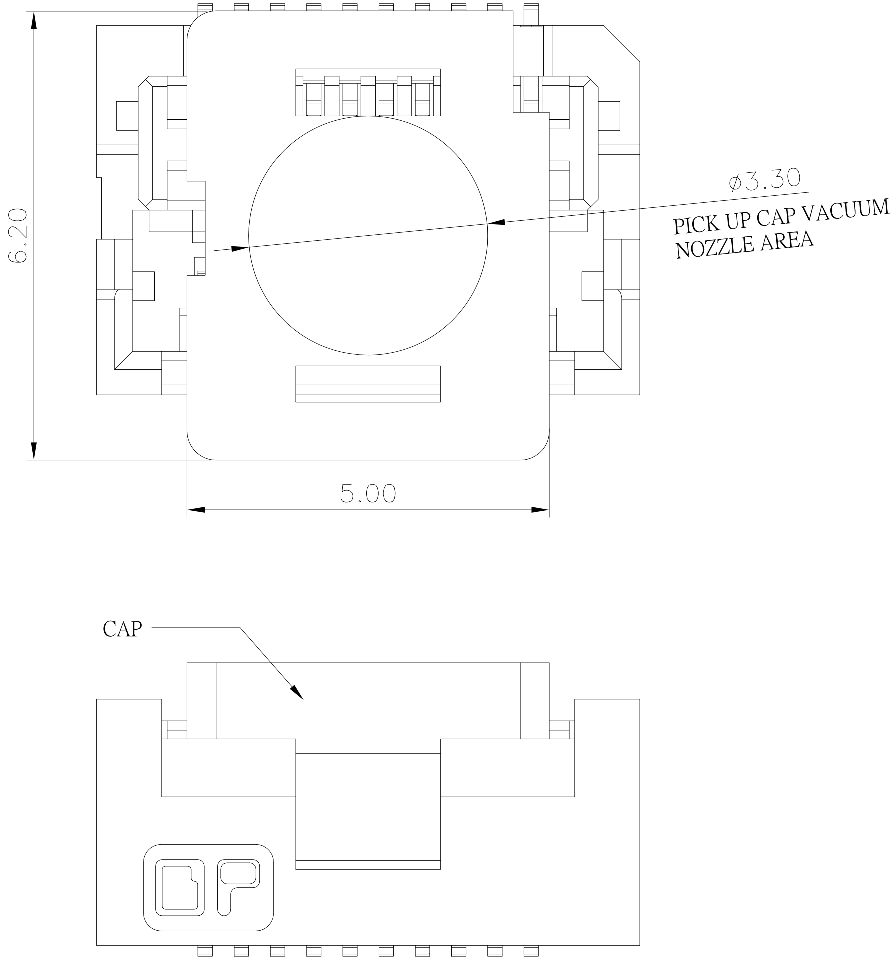
Title:
2330 Series
Board to Board High Speed
0.5mm pitch, Hermaphroditic

Ⓚ

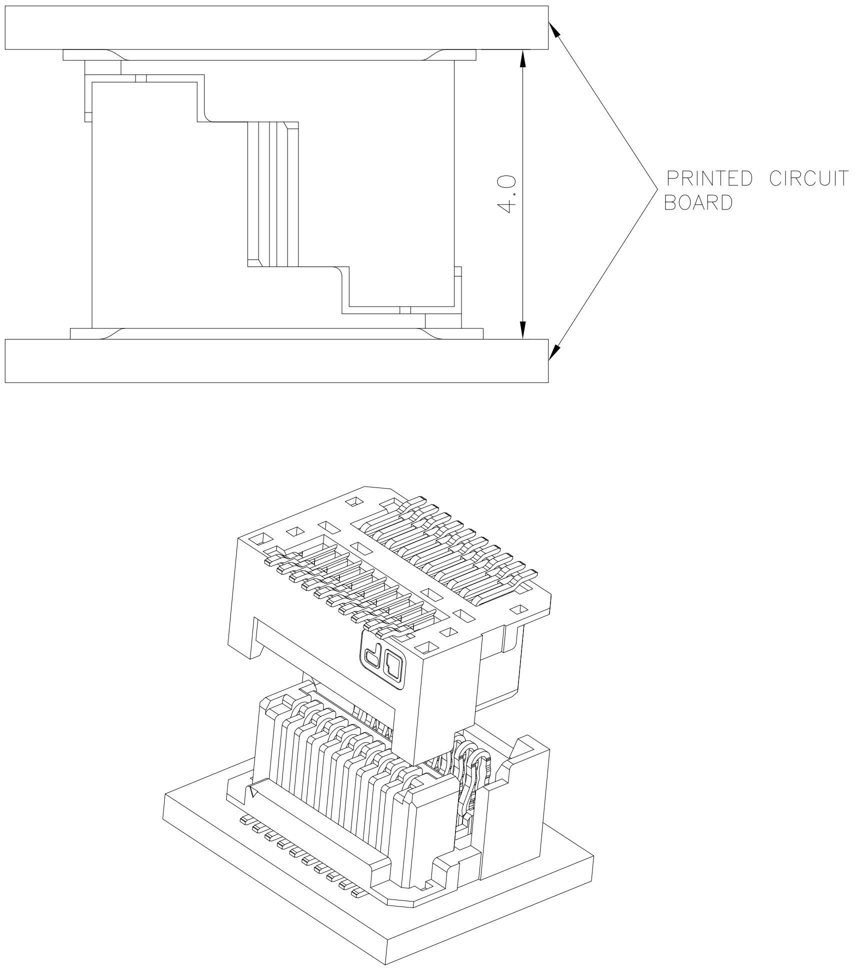
OUPIIN ELECTRONIC(KUNSHAN) CO., LTD.

P/N:	2330–20G15DN1T–P		
SHEET	1/2	Ver.No.	R2

REV.	SPECIFICATION	ECN NO.	APPD.
R2		ECN220358	



SHOWN WITH PICK-UP CAP



HERMAPHRODITIC CONNECTOR MATING

Tolerances	**Dwg. No.**	2330-DS20-001	**Title:**	OUPIIN ELECTRONIC(KUNSHAN) CO., LTD.
x = ±0.5 .x = ±0.25 .xx = ±0.15	**Projection**	⌖ ⊲	2330 Series Board to Board High Speed 0.5mm pitch, Hermaphroditic	**P/N:** 2330-20G15DN1T-P
	Unit mm	**Scale** 1:1		
	Drawn By	ZY 3/24'22		**SHEET** 2/2 **Ver.No.** R2